

REMARKS

In the present amendment claims 1-21 have been cancelled, claims 22-24 were
5 previously withdrawn and claims 25-28 have been added.

Rejection under 35 USC 103

Claim 1-5, 9-15 and 19-21 were rejected under 35 USC section 103 over Hinds
(EP1057779A2) in view of Kainuma (U.S. 6,483,190).

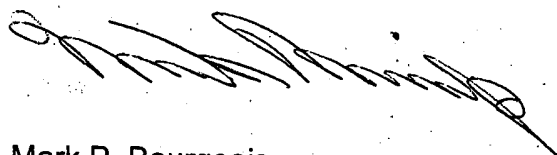
Neither Hinds, nor Kainuma, teach, disclose or suggest as in new claim 25, a
semiconductor package that includes a first reflowed solder paste for making an
electrical connection between a substrate and a semiconductor device and a
a wire bond bump located between the micro-machined semiconductor device and the
substrate to support the micro-machined semiconductor device during solder reflow.

The combination of Hinds and Kainuma teaches away from the present
invention. Hinds teaches using a cavity to space the semiconductor device from the
10 substrate and soldering to make an electrical connection between the semiconductor
device and the substrate. Kainuma teaches using stud bumps to make an electrical
connection. If Hinds and Kainuma were combined, the combination would require a
cavity to space active area of the semiconductor device away from the substrate. The
present invention clearly has no cavity. No cavity is required to be formed with the
15 present invention. The formation of the cavity requires extra processing steps and extra
layers of low temperature co-fired ceramic.

Dependent claims 26-28 depend from independent claim 25 and are allowable
therewith.

Respectfully submitted,

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